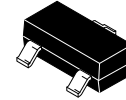


Dual Switching Diode Common Cathode

BAV70L, SBAV70L



SOT-23 (TO-236)
CASE 318
STYLE 9

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (EACH DIODE)

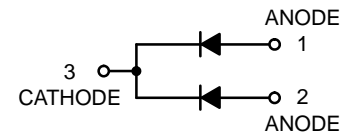
Rating	Symbol	Value	Unit
Reverse Voltage	V_R	100	V
Forward Current	I_F	200	mA
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I_{FRM}	1.5	A
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^\circ\text{C}$ prior to surge)	I_{FSM}		A
$t = 1 \mu\text{s}$		31	
$t = 10 \mu\text{s}$		16	
$t = 100 \mu\text{s}$		10	
$t = 1 \text{ ms}$		4.5	
$t = 10 \text{ ms}$		2.5	
$t = 100 \text{ ms}$		1.0	
$t = 1 \text{ s}$		0.5	

THERMAL CHARACTERISTICS

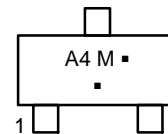
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



MARKING DIAGRAM



A4 = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BAV70LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBAV70LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BAV70LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SBAV70LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

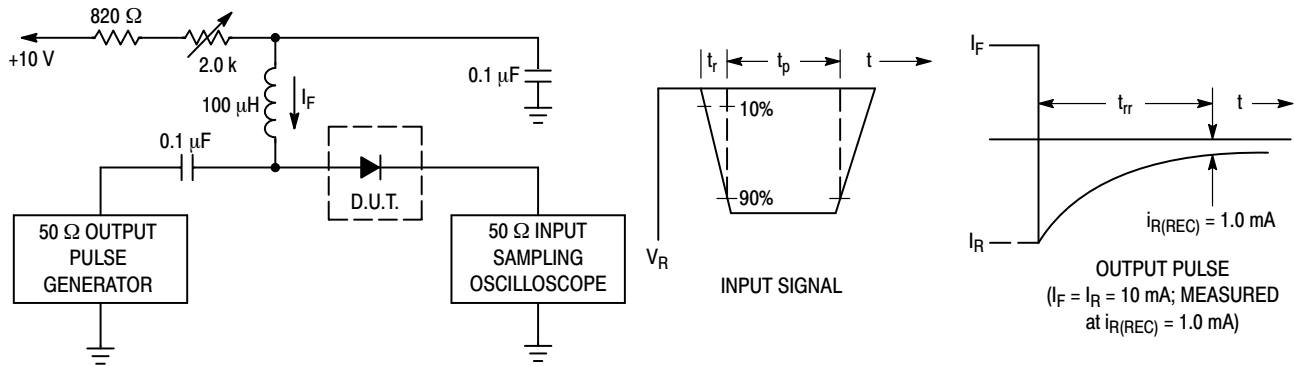
BAV70L, SBAV70L

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (Each Diode)

Characteristic	Symbol	Min	Max	Unit
Reverse Breakdown Voltage ($I_{(BR)} = 100 \mu\text{A}$)	$V_{(BR)}$	100	–	V
Reverse Voltage Leakage Current (Note 3) ($V_R = 25 \text{ V}$, $T_J = 150^\circ\text{C}$) ($V_R = 100 \text{ V}$) ($V_R = 70 \text{ V}$, $T_J = 150^\circ\text{C}$)	I_R	–	60 1.0 100	μA
Diode Capacitance ($V_R = 0 \text{ V}$, $f = 1.0 \text{ MHz}$)	C_D	–	1.5	pF
Forward Voltage ($I_F = 1.0 \text{ mA}$) ($I_F = 10 \text{ mA}$) ($I_F = 50 \text{ mA}$) ($I_F = 150 \text{ mA}$)	V_F	–	715 855 1000 1250	mV
Reverse Recovery Time $R_L = 100 \Omega$ ($I_F = I_R = 10 \text{ mA}$, $I_{R(REC)} = 1.0 \text{ mA}$) (Figure 1)	t_{rr}	–	6.0	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. For each individual diode while second diode is unbiased.



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.

3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BAV70L, SBAV70L

Curves Applicable to Each Anode

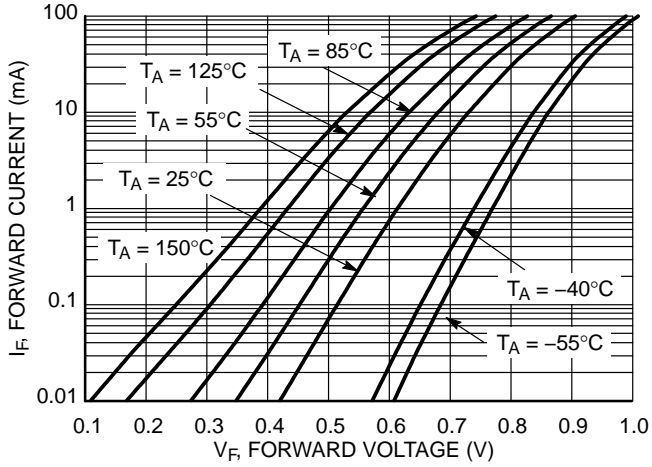


Figure 2. Forward Voltage

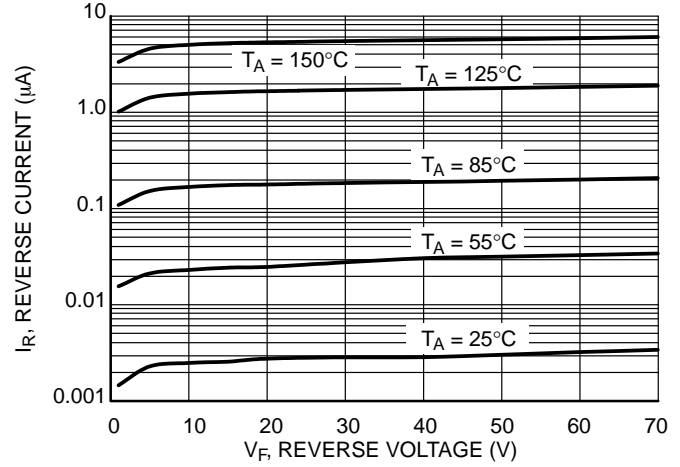


Figure 3. Leakage Current

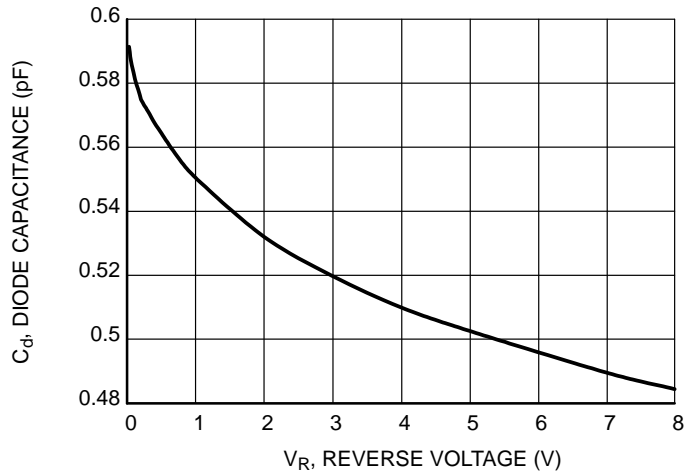
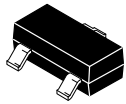


Figure 4. Capacitance

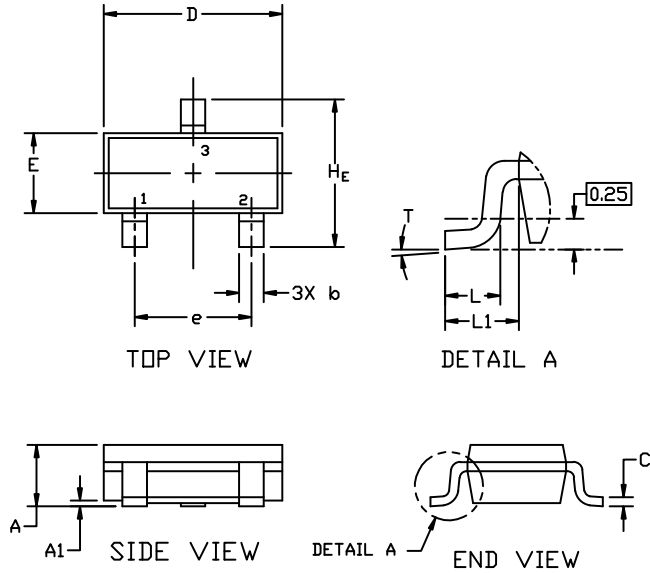
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

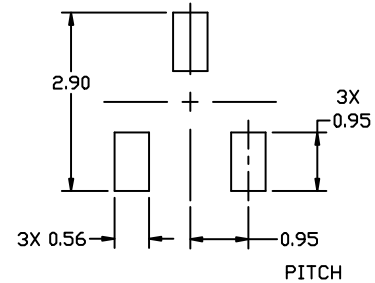
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H _E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5:
 CANCELLED

STYLE 6:
 PIN 1. BASE
 2. EMITTER
 3. COLLECTOR

STYLE 7:
 PIN 1. EMITTER
 2. BASE
 3. COLLECTOR

STYLE 8:
 PIN 1. ANODE
 2. NO CONNECTION
 3. CATHODE

STYLE 9:
 PIN 1. ANODE
 2. ANODE
 3. CATHODE

STYLE 10:
 PIN 1. DRAIN
 2. SOURCE
 3. GATE

STYLE 11:
 PIN 1. ANODE
 2. CATHODE
 3. CATHODE-ANODE

STYLE 12:
 PIN 1. CATHODE
 2. CATHODE
 3. ANODE

STYLE 13:
 PIN 1. SOURCE
 2. DRAIN
 3. GATE

STYLE 14:
 PIN 1. CATHODE
 2. GATE
 3. ANODE

STYLE 15:
 PIN 1. GATE
 2. CATHODE
 3. ANODE

STYLE 16:
 PIN 1. ANODE
 2. CATHODE
 3. CATHODE

STYLE 17:
 PIN 1. NO CONNECTION
 2. ANODE
 3. CATHODE

STYLE 18:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. ANODE

STYLE 19:
 PIN 1. CATHODE
 2. ANODE
 3. CATHODE-ANODE

STYLE 20:
 PIN 1. CATHODE
 2. ANODE
 3. GATE

STYLE 21:
 PIN 1. GATE
 2. SOURCE
 3. DRAIN

STYLE 22:
 PIN 1. RETURN
 2. OUTPUT
 3. INPUT

STYLE 23:
 PIN 1. ANODE
 2. ANODE
 3. CATHODE

STYLE 24:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE

STYLE 25:
 PIN 1. ANODE
 2. CATHODE
 3. GATE

STYLE 26:
 PIN 1. CATHODE
 2. ANODE
 3. NO CONNECTION

STYLE 27:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE

STYLE 28:
 PIN 1. ANODE
 2. ANODE
 3. ANODE

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